

Security code: 6258 November 2025

Financial Results Explanatory Materials

FY2025 (March 2026) Second quarter

Note: This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.



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%FY2025 represents the fiscal year ending March 31, 2026.

Hirata

Company Profile

Company Name	HIRATA Corporation
Address	111 Hitotsugi, Ueki, Kita, Kumamoto, 861-0198 Japan
Representatives	Yuichiro Hirata, President
Date Established	December 29, 1951
Capital	2,633 million yen
Our business	Manufacture and sales of various manufacturing systems, industrial robots and logistic equipment
Stock Exchange Listings	Tokyo Stock Exchange, Prime Market (Security Code : 6258)
Employees	Consolidated 2,365 Non-Consolidated 1,570 **As of September 30, 2025
Plants and office	7 bases in Japan(4 bases in Kumamoto 1 each in Tochigi, Shiga, Tokyo)
Subsidiaries	3 subsidiaries in Japan(2 in Kumamoto, 1 in Tokyo) 9 overseas subsidiaries(America、Mexico、Singapore、Malaysia、2 in China、 Taiwan、Thailand※、Germany※)

^{*} We are currently in the process of liquidating our affiliated companies in Thailand and Germany.





Financial Summary

- Received orders increased compared to the same period last year, driven by orders of large project related in the automobile-related business and continued demand for generative AI in the semiconductor-related business.
- Sales Sales increased compared to the same period last year, supported by improved production capacity, resulting in revenue growth in both the automobile- and semiconductor-related business.
- Operating profit increased compared to the same period last year, supported by higher sales and improved cost ratios in the automobile-related business and other automatic labor-saving equipment.

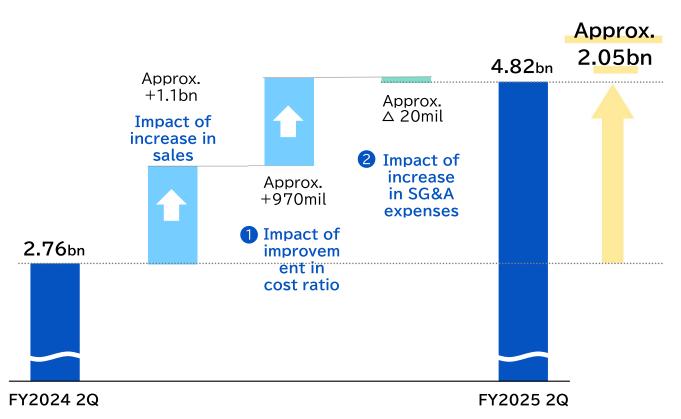
(Units in millions of Yen)

	FY2024 2Q	FY2025 2Q	YoY Change	
	Actual results	Actual results	Amount of +/-	Percentage of +/-
Received orders	43,975	43,429	▲ 545	▲1.2%
Net Sales	40,365	45,648	5,282	13.1%
Backlog of Orders	69,014	54,214	▲ 14,799	▲21.4%
Operating Profit (Profit ratio)	2,765 (6.8%)	4,822 (10.6%)	2,057	74.4%
Ordinary Profit	2,708	5,011	2,303	85.0%
Net income attributable to owners of the parent for the interim period	1,803	3,437	1,633	90.5%



Factor Analysis on Changing Operating Profit

- Operating profit increased approximately 2.05 billion yen from the same period of the previous year.
 - Main factors for increase: Increase in sales, Improvement in cost ratio
 - Main factors for decrease: Increase in the selling, general and administrative expenses



1 Impact of improvement in cost ratio

Cost ratio : 79.1% ⇒ **76.9%**

Main factors contributing to the improvement in cost ratio

- Promotion of price pass-through (mainly in automobile-related business)
- Improved profitability through enhanced proficiency (mainly in automobile-related business)
- 2 Impact of increase in SG&A expenses
 - There are no major fluctuations.

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Results by Segment

* Elimination of intersegment transactions is included in 'Others'.

(Uı	nits in millions of Yen)	FY2024 2Q	FY2025 2Q	Amount of +/-	Percentage of +/-
	Total	43,975	43,429	▲ 545	▲ 1.2%
Received orders	Automobile	24,733	24,374	▲ 358	▲ 1.5%
	Semiconductor	13,393	12,725	▲ 667	▲ 5.0%
	Other Automatic Labor- saving Equipment	4,724	5,177	453	9.6%
	Others	1,123	1,150	27	2.4%
	Total	40,365	45,648	5,282	13.1%
	Automobile	18,895	22,134	3,239	17.1%
Net Sales	Semiconductor	14,174	16,412	2,238	15.8%
	Other Automatic Labor- saving Equipment	6,186	5,979	▲207	▲3.3%
	Others	1,109	1,121	12	1.1%
	Total	69,014	54,214	▲ 14,799	▲21.4 %
	Automobile	44,988	32,442	▲ 12,545	▲27.9%
Backlog of	Semiconductor	18,689	15,327	▲ 3,362	▲ 18.0%
orders	Other Automatic Labor- saving Equipment	4,833	5,748	915	18.9%
	Others	502	695	193	38.5%
	Total	2,765	4,822	2,057	74.4%
	Automobile	1,298	3,248	1,950	150.1%
Operating	Semiconductor	1,801	1,045	▲ 756	▲ 42.0%
profit	Other Automatic Labor- saving Equipment	▲ 308	465	774	-
	Others	▲ 26	63 oration All Rights Reserved.	89	-



Results by Segment: Automobile-related business

- Received Received orders remained on par with the same period last year, driven by continued orders of large-scale projects related to orders internal combustion engines and automotive components in Q1 and Q2.
- Sales Sales increased compared to the same period last year, as production progressed mainly in internal combustion engine-related and battery-related projects.
- Operating profit increased compared to the same period last year, as profitability significantly improved due to higher sales, active promotion of price pass-through, and enhanced employee proficiency, in contrast to the previous year which saw higher development costs.

	FY2024 2Q		FY202	5 2Q	YoY Change		
		Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Receive	ed orders	24,733	-	24,374	-	▲ 358	▲ 1.5%
	EV	18,690	75.6%	12,326	50.6%	▲ 6,363	▲ 34.0%
	Others	6,042	24.4%	12,048	49.4%	6,005	99.4%
Net Sal	es	18,895	-	22,134	-	3,239	17.1%
	EV	12,794	67.7%	11,830	53.4%	▲ 964	▲ 7.5%
	Others	6,100	32.3%	10,303	46.6%	4,203	68.9%
Backlog	of orders	44,988	-	32,442	-	▲ 12,545	▲ 27.9%
Operatin	g profit	1,298	-	3,248	-	1,950	150.1%
Operating	profit ratio	6.9%	-	14.7%	-	-	-

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Results by Segment: Semiconductor-related business

Received orders Received orders remained on par with the same period last year, supported by continued demand for generative AI-related products.

Sales

Sales increased compared to the same period last year, as production progressed mainly in wafer transfer systems.

Operating profit Operating profit decreased compared to the same period last year, primarily due to a worsening cost ratio resulting from rising material costs and delays in price pass-through.

(Units in millions of Yen)

		FY2024 2Q		FY202	FY2025 2Q		YoY Change	
		Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-	
Receive	ed orders	13,393	-	12,725	-	▲ 667	▲ 5.0%	
	Wafer transfer	11,046	82.5%	9,403	73.9%	▲ 1,643	▲ 14.9%	
	Others	2,346	17.5%	3,322	26.1%	975	41.6%	
Net Sal	les	14,174	-	16,412	-	2,238	15.8%	
	Wafer transfer	9,871	69.6%	11,936	72.7%	2,064	20.9%	
	Others	4,302	30.4%	4,476	27.3%	173	4.0%	
Backlog	of orders	18,689	_	15,327	-	▲ 3,362	▲ 18.0%	
Operating profit		1,801		1,045	-	▲ 756	▲ 42.0%	
Operating	profit ratio	12.7%	-	6.4%	-	_	-	

Results by Segment: Other Automatic Labor-saving Equipment

- Received orders increased compared to the same period last year, driven by demand for organic EL products. Received orders
- Sales remained on par with the same period last year, although sales in home appliances-related business declined, organic EL-Sales related sales increased.
- Operating Operating profit increased compared to the same period last year, supported by higher sales of organic EL-related business profit with high proficiency, along with the completion of previously unprofitable projects.

(Units in millions of Yen)

	FY2024 2Q		FY2025 2Q		YoY Change	
	Results	Segment composition	Results	Segment composition	Amount of +/-	Percentage of +/-
Received orders	4,724	-	5,177	-	453	9.6%
Net Sales	6,186	-	5,979	-	▲ 207	▲ 3.3%
Backlog of orders	4,833	-	5,748	-	915	18.9%
Operating profit	▲ 308	-	465	-	774	-
Operating profit ratio	▲ 5.0%	-	7.8%	-	-	-

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Balance Sheet

Assets	FY2024	FY2025 2Q	YoY change
Current Assets	88,035	92,237	4,202
Cash & deposits	12,882	11,877	▲ 1,004
Accounts receivables	56,561	59,951	3,390
Inventories	15,510	18,084	2,574
Others	3,080	2,323	▲ 757
Non-Current Assets	42,243	42,888	645
Tangible fixed assets	26,592	26,281	▲311
Intangible fixed assets	1,160	1,174	13
Investment & other assets	14,489	15,432	942
Total Assets	130,278	135,126	4,847

Main factors for increase/decrease

- Accounts receivables increased due to the progress of production and increase in accounts receivable.
- Other current liabilities also increased as a result of higher contract liabilities.

Liabilities	FY2024	FY2025 2Q	YoY change
Current liabilities	43,295	46,785	3,489
Trade payables	10,574	9,828	▲ 746
Short-term borrowings [*]	22,330	22,273	▲ 57
Others	10,390	14,683	4,293
Fixed liabilities	18,143	17,593	▲ 550
Long-term borrowings	11,836	11,269	▲ 567
Others	6,307	6,324	16
Total Liabilities	61,439	64,378	2,939
Total Net Assets	68,839	70,747	1,908
Total Liabilities and Net Assets	130,278	135,126	4,847

* including long-term borrowings due within one year



II. FY2025 Full Year Forecasts (Consolidated)



Full Year Forecast

• We anticipate an increase in revenue to 96 billion yen and an increase in operating profit to 8.4 billion yen for the fiscal year 2025 (ending March 2026).

There is no change to the earnings forecasts for the fiscal year ending March 31, 2026, disclosed in May 2025.

(Units in millions of Yen)

	FY2024 FY2025		YoY Change	
_	Results	Full year forecast	Amount of +/-	Percentage of +/-
Net Sales	88,483	96,000	7,516	8.5%
Automobile-related business	43,059	43,000	▲ 59	▲0.1%
Semiconductor- related business	30,186	36,000	5,813	19.3%
Other Automatic Labor-saving Equipment	13,096	15,000	1,903	14.5%
Others	2,141	2,000	▲141	▲ 6.6%
Operating Profit (x)	6,898 (7.8%)	8,400 (8.8%)	1,501	21.8%
Ordinary Profit (x)	6,889 (7.8%)	8,200 (8.5%)	1,310	19.0%
Profit attributable to owners of parent (x)	4,778 (5.4%)	5,700 (5.9%)	921	19.3%



Highlights of Full Year Forecast - Net Sales

- For the fiscal year 2025, we forecast sales revenue to be 96 billion yen, an increase of 8.5% compared to the previous period (the highest ever).

 There is no change to the earnings forecasts
- We expect increased sales primarily in the semiconductor-related business.

There is no change to the earnings forecast for the fiscal year ending March 31, 2026, disclosed in May 2025.

- 1 Automobile-related business 43 billion yen (almost the same compared to the previous year)
- •We anticipate continued solid demand, primarily for ICE and EV batteries.
- As a core business for Hirata, we aim to improve productivity and ensure appropriate price pass-through.
- 2 Semiconductor-related business 36 billion yen (+5.8 billion yen compared to the previous year)
 - •We expect semiconductor demand related to generative AI to remain strong in fiscal year 2025.
 - •By developing new products and enhancing supply capacity, we will respond to market needs and aim to increase our market share.
- 3 Other Automatic Labor-saving Equipment 15 billion yen (+1.9 billion yen compared to the previous year)
 - •Leveraging our past experiences, we will focus on responding to high-profit inquiries.

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Transition and Forecast of Dividends and Dividend Ratio per Share

(Units in Yen)

		FY2020	FY2021	FY2022	FY2023	FY 2024	FY2025 forecast
Dividends per Share [*]		21.7	21.7	30.0	33.3	40.0	65.0
Consolidated dividend payou ratio(%)	t	16.6	25.2	21.9	23.9	25.9	35.3

Amount of treasury shares acquired :approx. 1 billion ven Total shareholder return ratio: 46.7%

<Our approach to dividends>

For dividends from the fiscal year 2025 onwards, based on the growth strategy aimed at enhancing corporate value as outlined in the medium-term management plan (FY2025-2027), we have established the allocation of growth investments and shareholder returns within our cash allocation policy, and decided to raise the target consolidated dividend payout ratio to a level from 20% to 35%.

For the fiscal year 2025's dividend, we anticipate a year-end dividend of 65 yen.

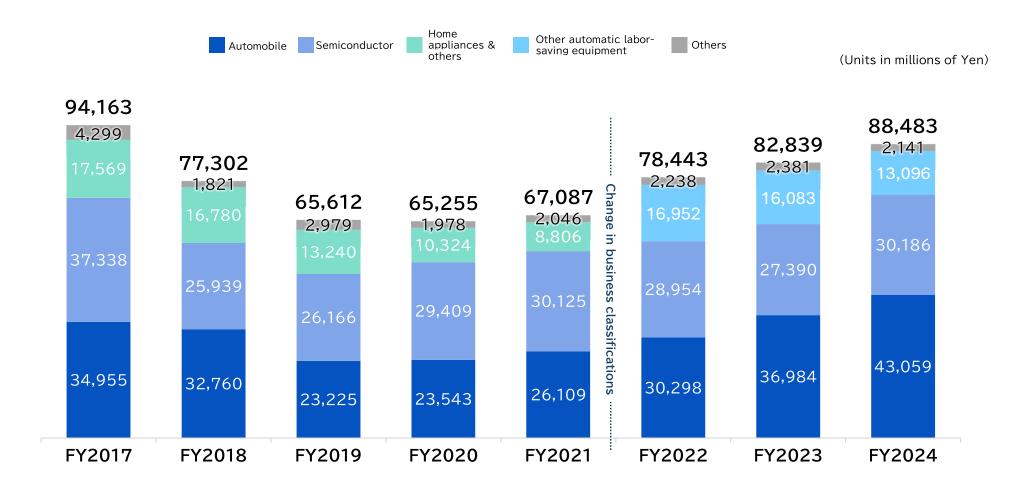
*The dividends per share reflects the impact of the share split (three-for-one), which became effective on April 1, 2025.



III. Reference Data

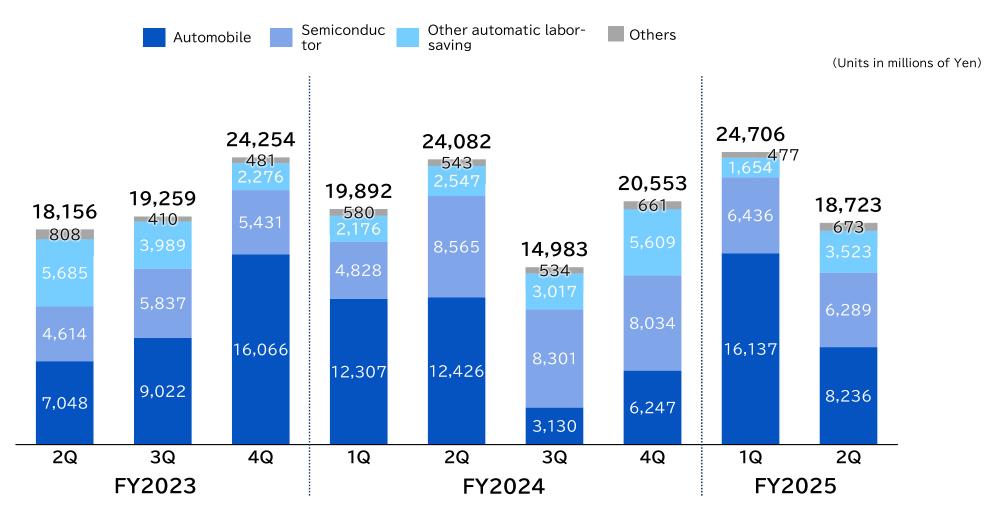


Net Sales by Business Segment (FY2017 to FY 2024)



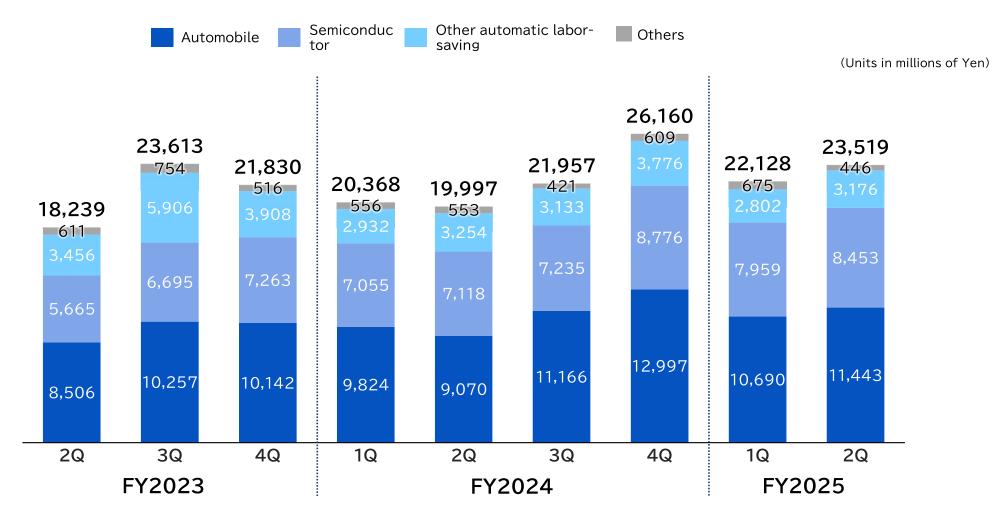
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Received Orders by Business Segment (Quarterly Trends)





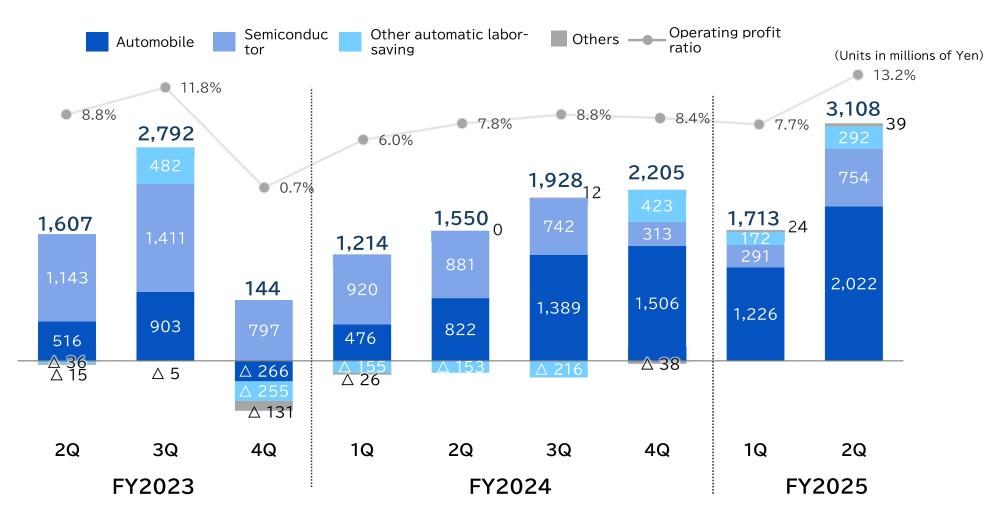
Net Sales by Business Segment (Quarterly Trends)



III. Reference Data 4

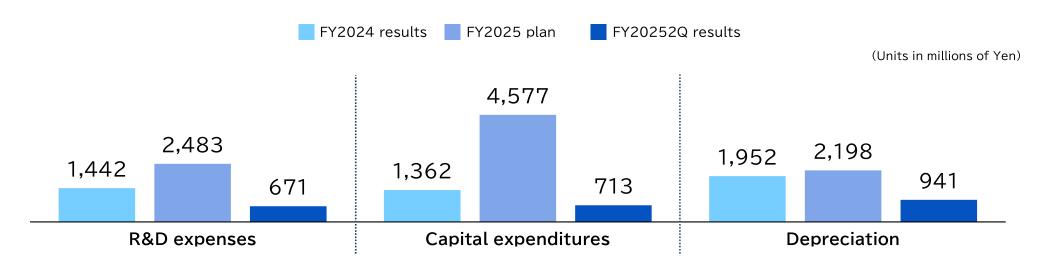
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Operating Profit by Business Segment (Quarterly Trends)





R&D expenses, CAPEX, and Depreciation expenses

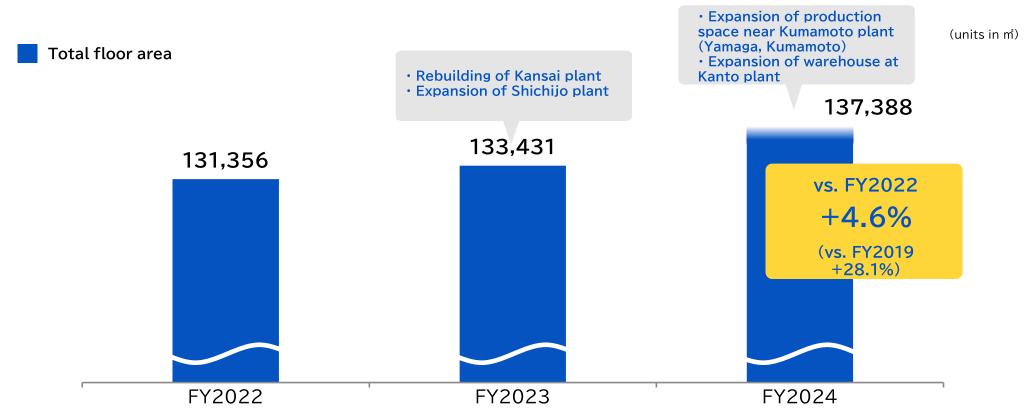


	FY2024 results	FY2025 plan	Reasons of increase/decrease
R&D expenses	1,442 million yen	2,483 million yen	 Promote the development of mass-produced products
Capital expenditures	1,362 million yen	4,577 million yen	 Enhance production and development capabilities



Production space (Non-consolidated • End of period)

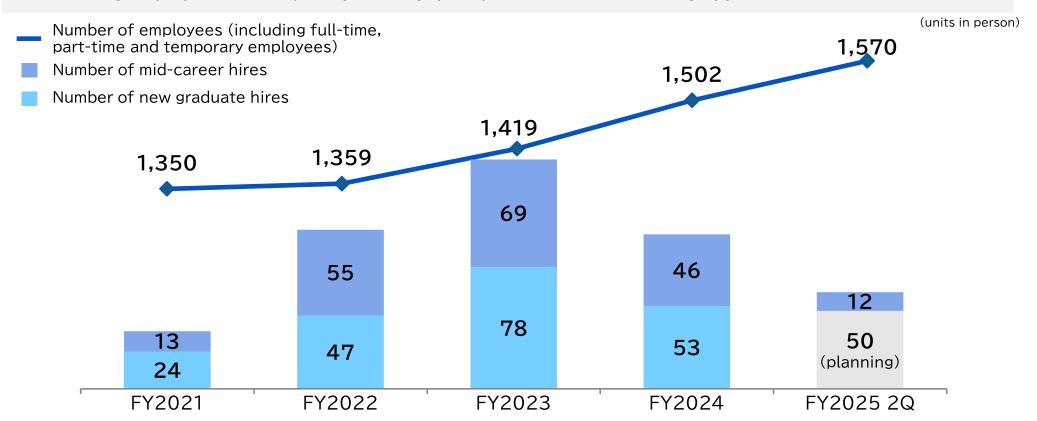
- We are actively working on the continuous expansion of production space to increase our production capacity.
- We secured production space in Yamaga City, which is adjacent to Kumamoto City, for the fiscal year 2024 as well.



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Number of recruits · employees (Non-consolidated · End of period)

- In anticipation of business expansion, we are committed to ensuring a continuous supply of talented professionals.
- We are working on talent retention through various measures such as wage improvements, workstyle reforms, enhancing employee benefits, and providing quality education and training opportunities.





External Environment and growth opportunities

Changes in the environment surrounding Hirata

Serious deepening of labor shortages Surge in labor costs

Innovations in digital technologies centered around AI

Partial slowdown in the growth of the EV market
Automakers' all-around strategies

Expansion of the semiconductor market and rapid technological evolution

Growing importance of sustainability

Demands for enhancing corporate value from the market

Implications for our business

Expansion of automation and labor-saving needs

Shift towards building equipment based on digitalization in production sites

Response to advanced automation needs across a wide range of automobile-related equipment

Development of high valueadded products in response to changing customer needs

Product development and business cultivation that meet needs such as reducing environmental impact

Early realization of a highprofit structure through the pursuit of earning power

Hirata's strengths

Long-term relationships with global top companies

Expertise, technologies, and resources developed as a manufacturer of production equipment

Ability to continuously meet customer needs for over 70 years

A trusted position in an industry with high barriers to entry

Role recognition

We recognize that expectations for our automation and labor-saving solutions from customers will continue to grow.



Topic: Receipt of large project orders

The list of large-scale purchase order projects we disclosed started from FY2023 and onwards

Business segment	Disclosure date		Outline of the equipment	Amount
	2023	June	EDU assembly equipment for EVs	More than 8 billion yen
Automobile -related	2024	January	Battery charging and discharging related equipment for EVs	More than 4 billion yen
business		February	Engine assembly equipment for internal combustion engines	Approximately 13 billion yen
		May	Battery charging and discharging related equipment for EVs	Approximately 2.5 billion yen
		August	Battery charging and discharging related equipment for EVs	Approximately 5.6 billion yen
		August	EDU assembly equipment for EVs	Approximately 8.7 billion yen
	2025	May	Engine assembly equipment for internal combustion engines	Approximately 10 billion yen
		September	Assembly equipment for automotive electronic components	More than 6 billion yen

[•] We have been continuously receiving large-scale projects due to our ability to handle such projects and our proven track record of successful deliveries..



Strengthening our efforts in ESG management

_		
2023	Apr.	The Sustainability Promotion Committee is established.
		Sustainability page is established in our web page and the dissemination of ESG information is been strengthened. WE SUPPORT
	Sep.	We sign the UN Global Compact.
	Oct.	Human rights due diligence is implemented.
	Nov.	We express our support for the Keidanren's "Charter of Corporate Behavior."
2024	Jan.	Code of Conduct of the Hirata Group is established.
		Human Rights Respect Working Group within the Sustainability Promotion Committee is established. FTSE Blossom Japan Index
	Jun.	Selected as a constituent stock for: 「FTSE Blossom Japan Index」 FTSE Blossom Japan Sector FTSE Blossom Japan Sector Relative Index
	Nov.	We have endorsed the Keidanren Declaration for Biodiversity and Guideline.
2025	Mar.	We have obtained the "Silver" rating in the EcoVadis sustainability assessment.

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Hirata Business Overview: Main products of automobile-related business

• We continue to receive orders from North American automakers (Big three), North American emerging EV manufacturers, domestic electronic components manufacturers, focusing on EV related.

Main/Expansion Fields of EV-related business

Production equipment handled by Hirata



*Completed product image

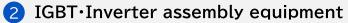
EDU assembly equipment

We manufacture EV-drive parts assembly equipment called EDU (Electric Drive Unit) combined with in-vehicle motors and gearboxes.

Main field







We manufacture in-vehicle electronic components mounted on EVs and transmissions such as IGBT and inverters.





Battery-related assembly equipment

(Cell charging / discharge process)

We manufacture conveying equipment for charging and discharging processes that are part of the battery cell progress.



Major markets, customers and competitive advantages

EDU assembly equipment

North America

Customers

- North American automakers (Big three)
- North American emerging EV manufacturers

IGBT·Inverter assembly equipment

Japan

Customers

Domestic electronic

components manufacturers

Battery-related assembly equipment

(cell charging/discharging process)

Japan

Customers

Domestic battery manufacturers

Hirata's competitive advantages

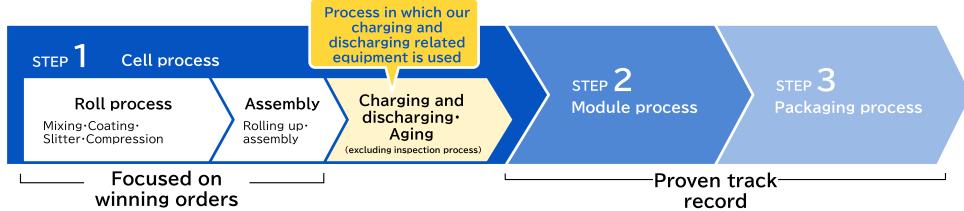
- Technical capabilities to handle large facilities, some of which exceed 1 km in total length, solely in-house
- A vast factory that allows us to build the customer's production line in our factory and install it on site after verifying the production capacity and quality
- Integrated system from development to production and maintenance
- Engineering ability to respond to customer requests

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Business Overview: Charging and discharging related equipment

- This is equipment related to charge-discharge processes, which are responsible for the final stage of cell manufacturing: charging, discharging, and aging.
- We have a competitive advantage in systematization utilizing conveyance and stocking technologies.

Battery manufacturing process



Our products:

Charging and discharging related equipment

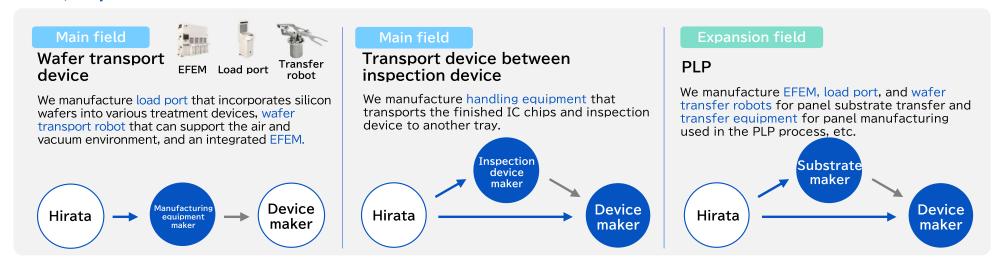
- The process of activating assembled cells (batteries) by repeatedly charging and discharging it to give it the functionality of a battery.
- We deliver the system to the customer by incorporating the charging and discharging machines procured from external suppliers into the transport lines and automated warehouses manufactured by us.
- The differentiating factor is our conveying and storage technology.

Transport system	This system provides optimal transfer between processes.
Warehouse system for aging	The system performs tests in high-temperature environments and measures the performance of cell voltages after a certain period of time in an automated warehouse.
Warehouse system for charging and discharging	It is used in a process in which a full charge and discharge are repeated several times. It takes several hours to set the charging capacity, charging speed, and number of repetitions.

Business Overview: Main products of semiconductor-related business

• We continue to receive orders mainly for wafer transport devices and handling devices between inspection devices for domestic device manufacturers.

Main/Expansion Fields of Semiconductor-related business



Major markets, customers and competitive advantages

Wafer transport device

Japan

Customers

Domestic manufacturing equipment manufacturers

Transport device between inspection device

North America, Japan **Customers**

- · North American device makers
- Domestic inspection equipment manufacturers

PLP

North America, Europe, Japan Customers

- · North American device makers
- · Domestic/European substrate manufacturers

Hirata's competitive advantages

- A wealth of component lineup
- Knowledge technology required for customization and optimization to meet customer requirements
- Integrated system from development to production and maintenance
- Engineering ability to respond to customer requests



Business Overview : Wafer transport device

• We design and manufacture load ports that take wafers into various processing equipment mainly used in the frontend process of semiconductor manufacturing, wafer transfer robots that transfer wafers, and EFEMs that integrate them.

Semiconductor manufacturing process

Process in which our wafer transfer devices are primarily used

Design

- Design for circuit and pattern
- Photomask creation

Front-end process

- · Wafer fabrication
- Making circuit pattern
 - •Oxidation of wafer surface
 - ·Thin film formation
 - ·Pattern transcription of photomask
 - ·Ion implantation

Back-end process

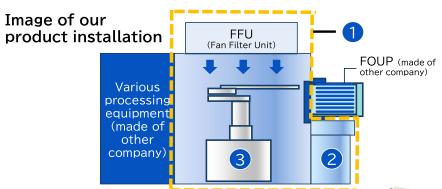
- Dicing
- Die bonding
- · Wire bonding
- Packaging
- Commercialization and final inspection

Image of our product installation



Multiple EFEM/load ports are used on a single line because multiple EFEM/load ports are installed at each processing unit.

Our main products



- 1 EFEM (Equipment Front End Module)
 It is placed for each processing unit, with a wafer transfer robot inside and a load port on the front.
- 2 Load port
 It opens and closes the lid on the back side of the FOUP **, a device that makes up the EFEM, but is also sold as a stand-alone item.
- Wafer transport robot
 Wafers are removed from the FOLL

Wafers are removed from the FOUP and transferred to the processing equipment. After processing, the wafers are stocked back in the FOUP. It is a device that makes up the EFEM, but is also sold as a standalone item.



item. ****FOUP**: It is a container for wafers that holds multiple wafers and moves them between processes

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Business Overview: PLP

• We design and manufacture conveyance equipment used in PLP, an advanced packaging technology that is expected to expand.

Semiconductor manufacturing process

Process in which our devices are primarily used

Design

Front-end process

- Design for circuit and pattern
- Photomask creation
- Wafer fabrication
- Making circuit pattern
 - Oxidation of wafer surface
 - •Thin film formation
 - ·Pattern transcription of photomask
 - ·Ion implantation

Back-end process

- Dicing
- Die bonding
- · Wire bonding
- Packaging
- Commercialization and final inspection

Difference of packaging process

Conventional packaging

Circuits are formed on wafers, and after cutting the chips into smaller pieces, they are individually bonded and encapsulated onto substrates to complete the product.

WLP

(Wafer Level Package)

After cutting the chips individually, only the good chips are rearranged on the wafer, and then they are bonded and encapsulated onto the substrate while the chips are still on the wafer. They are then cut individually.

PLP (Panel Level Package)

After cutting the chips individually, only the good chips are rearranged on a square-shaped panel, and then they are bonded and encapsulated onto the substrate while the chips are still on the panel. They are then cut individually.

What is PLP (Panel Level Packaging) about?

- The packaging process involves rearranging numerous chips that have been individually cut after circuit formation onto thin, square-shaped substrates and then collectively molding them. This is a packaging technology called "PLP".
- In PLP, panel substrates larger than the standard 300mm wafer size, such as 510x515mm square, are commonly used.
- The panel substrate uses printed circuit boards, glass substrates for LCD panel manufacturing, and copper plates.

The chips that have been rearranged.



200mm 300mm



WLP

PLP

Business Overview: Other Automatic Labor-saving Equipment

• We manufacture products for various industrial fields such as organic EL vapor equipment, assembly equipment for home appliances, and medical physics and chemical equipment.

Main/New Fields of Other Automatic Labor-saving Equipment

Main field

Medical physiology and chemical equipment

We manufacture a system for sample tests (pathological tissue specimen device and fully automatic continuous thinning device).

Main field

Assembly equipment for home appliances

We manufacture all equipment, including motor assembly equipment built into high-performance home appliances.

Organic EL Vapor Equipment

We are contracted to manufacture vacuum evaporation equipment for OLED panels.

New field for monetization

Focused ultrasound therapy equipment

- We are jointly developing a focused ultrasound treatment device targeting pancreatic cancer with SONIRE Therapeutics Inc (Headquartered in Shinjuku, Tokyo, hereinafter referred to as SONIRE).
- We aim for non-invasive cancer treatment that fuses SONIRE's Ultrasonic Technology with our robot technology.
- Clinical trials in humans have started, and we have begun development of the next generation of mass production equipment.

Major markets, customers and competitive advantages

Medical physiology and chemical equipment

Japan

Customers

Domestic medical specialty manufacturers

Assembly equipment for home appliances

Asia

Customers

Asian home appliance manufacturers

Organic EL Vapor equipment

Japan

Customers

Domestic manufacturing device manufacturers

Hirata's competitive advantages

- Extensive knowledge and expertise in production facilities and equipment in various fields
- Integrated system from development to production and maintenance
- Engineering ability to respond to customer requests

III. Reference Data 17 Hirata

Business Overview: High-Intensity Focused Ultrasound (HIFU) cancer treatment device

• We are applying our experience in specimen examination automation and robotics technology in the medical and scientific equipment field to enter the "treatment" domain.

Hirata's existing business Biotechnology equipment department

Automation technology for specimen examination



Over 20 years of experience in medical devices (Class I: General medical devices)

New partner SONIRE Therapeutics Inc. (SONIRE)

Clinical, clinical trial, and focused ultrasound technology

Technologies developed over more than 10 years in collaboration with Tokyo Women's Medical University, Tohoku University, and Tokyo Medical University

> Hirata's existing technology **Robot division**

Robot technology

Achievements in industrial robotics

Entering new fields of business

SONIRE conducts clinical trials, while Hirata establishes the manufacturing system.

Joint development of cancer treatment devices

Aim for sales launch and mass production (Class Ⅲ: Highly managed medical devices)



- Hirata partners with SONIRE Therapeutics Inc. (SONIRE) in the medical and scientific equipment field.
- We conduct joint development of a cancer treatment device for clinical trials in humans (targeting inoperable pancreatic cancer)
- We develop device for minimally invasive treatment that does not involve skin incisions or organ removal.
- The devices are supplied to multiple domestic hospitals, and SONIRE is conducting domestic clinical trials. Hirata is providing after-sales service post-delivery.
- In the future, we aim to refine the device's safety, usability, and design, and work towards the development of mass-produced devices and the establishment of a mass production system.
- We are planning to expand overseas, aiming for early delivery to overseas hospitals and after-sales service at our overseas locations.



Cautionary statement with this document

Please be aware that the performance forecasts and future predictions mentioned in this document are based on the information available to us at the time of its creation. They are subject to potential risks and uncertainties, such as changes in economic conditions, competition with other companies, and exchange rates. Therefore, please note that actual performance may significantly differ from the future outlook mentioned or described in this document due to various factors, including changes in the business environment.